Amendments to the Specification

Please delete paragraphs **[0018]**, **[0027]**, **[0028]**, and **[0029]** in their entirety and replace them with the following like numbered paragraphs:

[0018] **FIG. 2** illustrates an enlarged view of a fan module of **FIG. 1** in accordance with an embodiment of the present invention. Fan module 22 may have a module front end 33 and a module rear portion 34, and may be configured to be removable from the modular platform (not shown). The fan module has a width 35, and a height 28 as illustrated in FIG. 1. A plurality of fans 30, 30', 32, and 32' may be positioned at or near the rear portion 34 in an in-plane matrix array.

[0027] As with the symmetric fan modules discussed above, asymmetric fan modules may be configured to support a certain number of modular platform boards. The number of modular platform boards that an individual fan module may support may be equal to (y/x) m, where m is the total number of potential modular platform boards, y is the number of side-by-side fans in the fan module, and x is the number of side-by-side fans from all modules that may be disposed across the aggregate width. Considering the example in ~~FIG. 3~~ FIG. 4, y equals three fans side-by-side, and x equals five fans side-by-side spanning the aggregate width 76. Accordingly, fan module 74 may support 3/5m boards. Likewise, fan module 72 may support 2/5m boards.

[0028] Where the fan modules are symmetrically configured in the number of fan units per module, such as 2 X 2, it has been found that even though each module may be configured to support a certain number of boards, with one fan module removed, the remaining module can support more boards at a reduced airflow rate, which has been found to be approximately 70%. The same may be true for asymmetric fan modules, such as the example embodiment shown in ~~FIG. 3~~ FIG. 4. The airflow rate may be even higher than 70% depending on which tray is removed. Accordingly, despite the reduced airflow rate when a fan module is removed, airflow still is induced and the

modular platform boards may still transfer heat and resist overheating for longer periods of time.

[0029] Using the asymmetric configuration of ~~FIG. 3~~ FIG. 4 may allow for a plurality of smaller diameter fans to be used in the fan modules. By using a smaller diameter fan, the vertical dimension of the module may be less, which in turn may reduce the plenum size. Plenum size reduction may have benefits in certain Specifications, such as in the ATCA Specification. Existing telecom racks, in which ATCA shelves may be positioned, are typically 42U in height, where 1U is approximately equal to 44 mm. Having five fan units evenly distributed across the aggregate width 76 of the shelf allows use of fans having an overall diameter of approximately 88 mm, which is approximately 2U. Thus, a plenum height may be 2U, which has been found to allow for maximizing the use of rack space and allow for more flexibility in rack and individual shelf configurations.